

P-channel 20 V, 0.0195 Ω typ., 8 A STripFET™ VII DeepGATE™ Power MOSFET in a PowerFLAT™ 2x2 package

Datasheet - production data

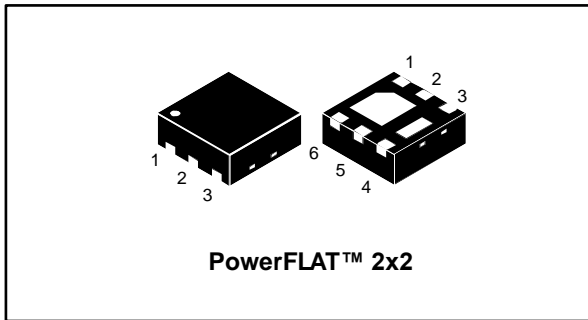
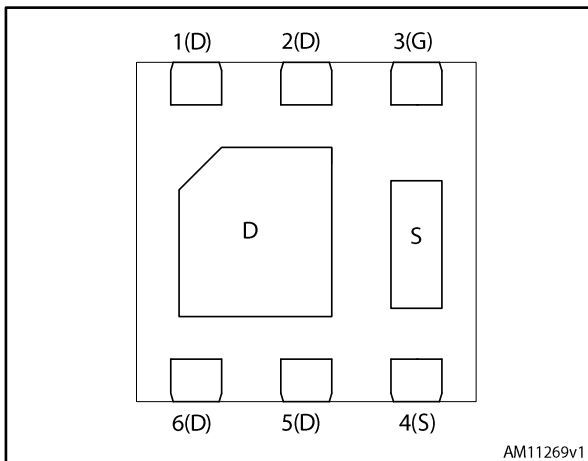


Figure 1: Internal schematic diagram



Features

| Order code | V_{DS} | $R_{DS(on)max}$ | I_D |
|------------|----------|-------------------------|-------|
| STL8P2UH7 | 20 V | 0.0225 Ω @ 4.5 V | 8 A |

- Extremely low on-resistance $R_{DS(on)}$
- Ultra logic level

Applications


- Switching applications

Description

This device exhibits low on-state resistance and capacitance for improved conduction and switching performance.

Table 1: Device summary

| Order code | Marking | Package | Packaging |
|------------|---------|----------------|---------------|
| STL8P2UH7 | 8L2U | PowerFLAT™ 2x2 | Tape and reel |

 For the P-channel Power MOSFET the actual polarity of the voltages and the current must be reversed.

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1 Electrical ratings

Table 2: Absolute maximum ratings

| Symbol | Parameter | Value | Unit |
|----------------|--|-------------|------------------|
| V_{DS} | Drain-source voltage | 20 | V |
| V_{GS} | Gate-source voltage | ± 8 | V |
| I_D | Drain current (continuous) at $T_{pcb}= 25\text{ }^\circ\text{C}$ | 8 | A |
| I_D | Drain current (continuous) at $T_{pcb}= 100\text{ }^\circ\text{C}$ | 5.3 | A |
| $I_{DM}^{(1)}$ | Drain current (pulsed) | 32 | A |
| P_{TOT} | Total dissipation at $T_{pcb}= 25\text{ }^\circ\text{C}$ | 2.4 | W |
| T_{stg} | Storage temperature | - 55 to 150 | $^\circ\text{C}$ |
| T_j | Max. operating junction temperature | 150 | $^\circ\text{C}$ |

Notes:

⁽¹⁾Pulse width limited by safe operating area

Table 3: Thermal data

| Symbol | Parameter | Value | Unit |
|---------------------|-------------------------------------|-------|--------------------|
| $R_{thj-pcb}^{(1)}$ | Thermal resistance junction-pcb max | 52 | $^\circ\text{C/W}$ |

Notes:

⁽¹⁾When mounted on 1inch² FR-4 board, 2 oz Cu



For the P-channel Power MOSFET the actual polarity of the voltages and the current must be reversed.

2 Electrical characteristics

(T_C = 25 °C unless otherwise specified)

Table 4: On /off states

| Symbol | Parameter | Test conditions | Min. | Typ. | Max. | Unit |
|----------------------|------------------------------------|---|------|--------|--------|------|
| V _{(BR)DSS} | Drain-source breakdown voltage | V _{GS} = 0, I _D = 250 μA | 20 | | | V |
| I _{DSS} | Zero gate voltage drain current | V _{GS} = 0, V _{DS} = 20 V | | | 1 | μA |
| I _{GSS} | Gate-body leakage current | V _{DS} = 0, V _{GS} = ± 5 V | | | ± 5 | μA |
| V _{GS(th)} | Gate threshold voltage | V _{DS} = V _{GS} , I _D = 250 μA | 0.4 | | 1 | V |
| R _{DS(on)} | Static drain-source on- resistance | V _{GS} = 4.5 V, I _D = 4 A | | 0.0195 | 0.0225 | Ω |
| | | V _{GS} = 2.5 V, I _D = 4 A | | 0.02 | 0.025 | Ω |
| | | V _{GS} = 1.8 V, I _D = 4 A | | 0.036 | 0.043 | Ω |
| | | V _{GS} = 1.5 V, I _D = 4 A | | 0.05 | 0.085 | Ω |

Table 5: Dynamic

| Symbol | Parameter | Test conditions | Min. | Typ. | Max. | Unit |
|------------------|------------------------------|--|------|------|------|------|
| C _{iss} | Input capacitance | V _{GS} = 0, V _{DS} = 16 V, f = 1 MHz | - | 2390 | - | pF |
| C _{oss} | Output capacitance | | - | 220 | - | pF |
| C _{rss} | Reverse transfer capacitance | | - | 188 | - | pF |
| Q _g | Total gate charge | V _{DD} = 16 V, I _D = 8 A, V _{GS} = 4.5 V | - | 22 | - | nC |
| Q _{gs} | Gate-source charge | | - | 4.2 | - | nC |
| Q _{gd} | Gate-drain charge | | - | 3.6 | - | nC |



For the P-channel Power MOSFET the actual polarity of the voltages and the current must be reversed.

Table 6: Switching times

| Symbol | Parameter | Test conditions | Min. | Typ. | Max | Unit |
|---------------------|---------------------|--|------|------|-----|------|
| t _{d(on)} | Turn-on delay time | V _{DD} = 16 V, I _D = 8 A, R _G = 1 Ω, V _{GS} = 4.5 V | - | 12.5 | - | ns |
| t _r | Rise time | | - | 30.5 | - | ns |
| t _{d(off)} | Turn-off delay time | | - | 128 | - | ns |
| t _f | Fall time | | - | 84.5 | - | ns |

Table 7: Source drain diode

| Symbol | Parameter | Test conditions | Min. | Typ. | Max. | Unit |
|-----------------|-------------------------------|---|------|------|------|------|
| I_{SD} | Source-drain current | | - | | 8 | A |
| $I_{SDM}^{(1)}$ | Source-drain current (pulsed) | | - | | 32 | A |
| $V_{SD}^{(2)}$ | Forward on voltage | $V_{GS}=0, I_{SD}=1\text{ A}$ | - | | 1 | V |
| t_{rr} | Reverse recovery time | $V_{DD}=16\text{ V}$ $di/dt = 100\text{ A}/\mu\text{s}$, $I_{SD}=1\text{ A}$ | - | 15.8 | | ns |
| Q_{rr} | Reverse recovery charge | | - | 5.9 | | nC |
| I_{RRM} | Reverse recovery current | | - | 0.7 | | A |

Notes:

⁽¹⁾Pulse width limited by safe operating area.

⁽²⁾Pulsed: pulse duration = 300 μs , duty cycle 1.5%



For the P-channel Power MOSFET the actual polarity of the voltages and the current must be reversed.

2.1 Electrical characteristics (curves)

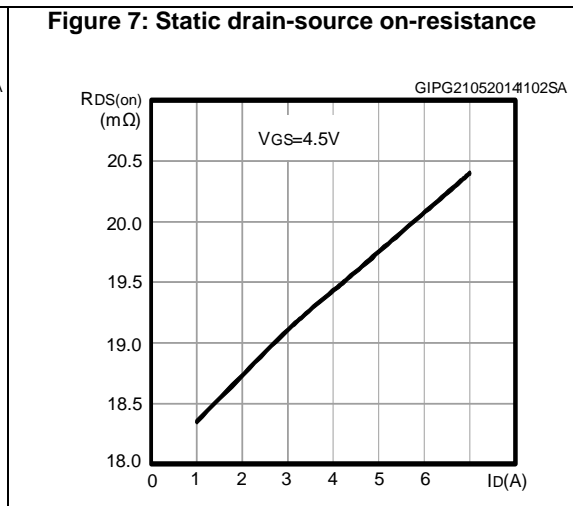
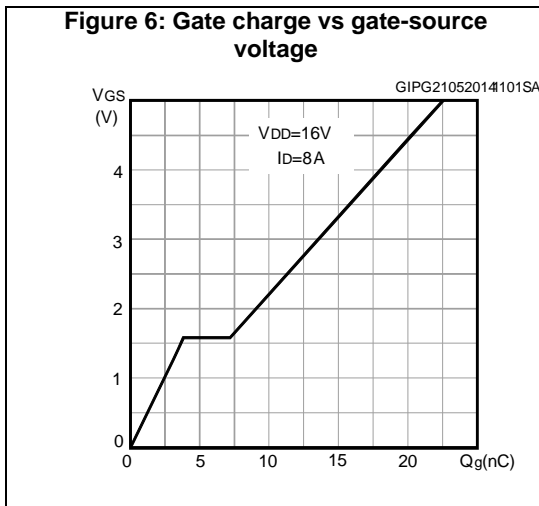
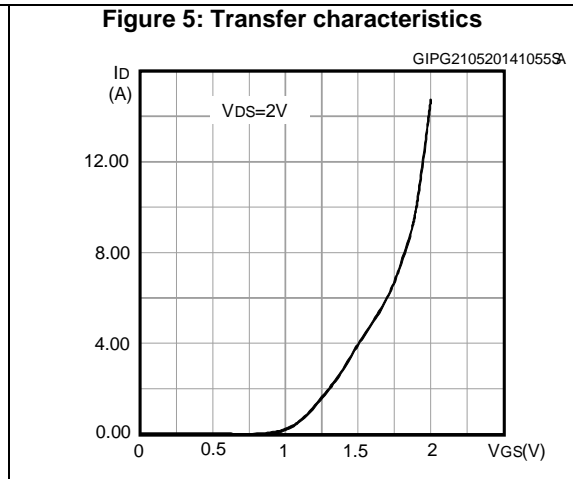
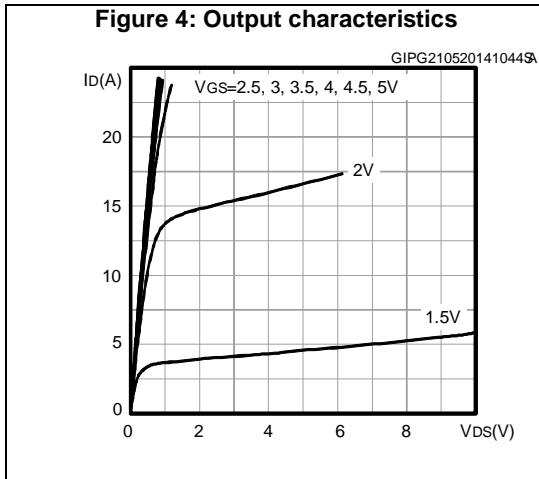
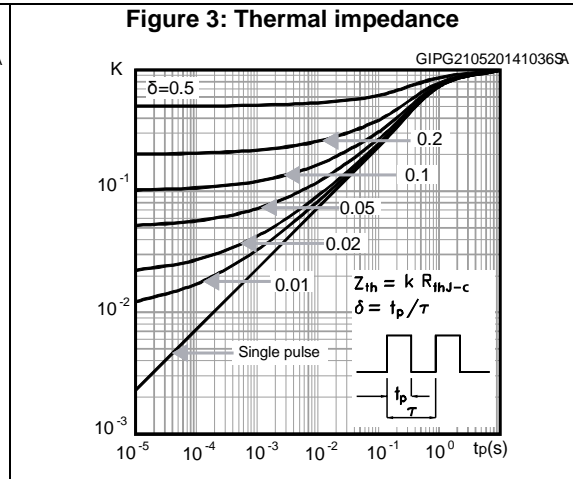
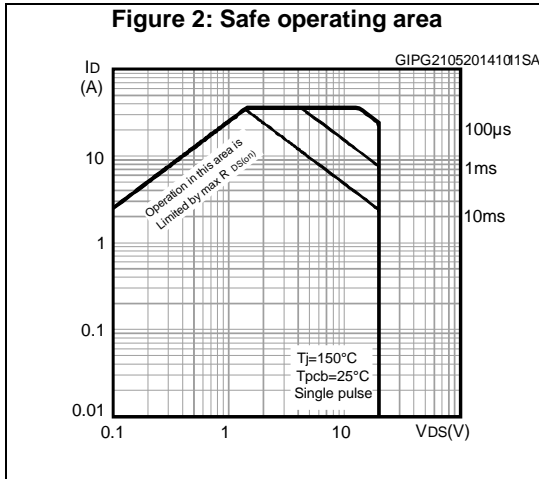


Figure 8: Capacitance variations

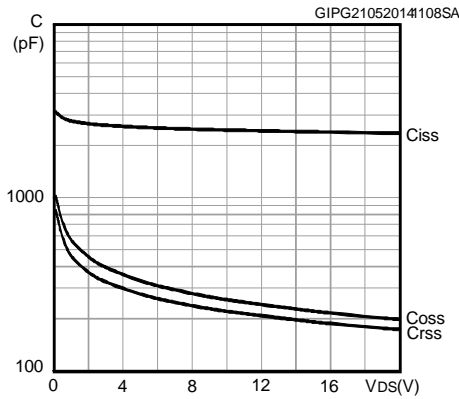


Figure 9: Normalized gate threshold voltage vs temperature

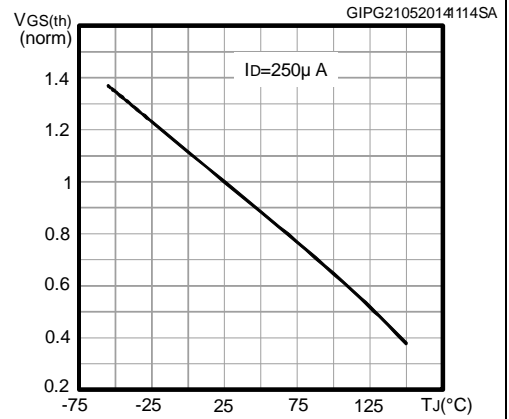


Figure 10: Normalized on-resistance vs temperature

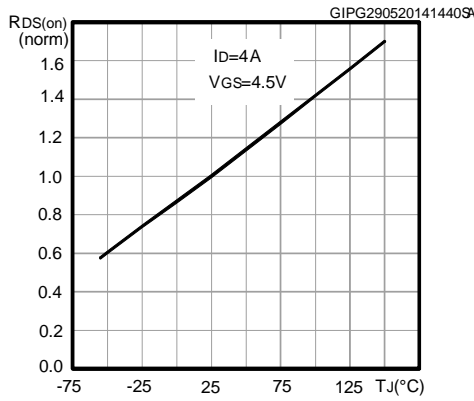


Figure 11: Normalized V(BR)DSS vs temperature

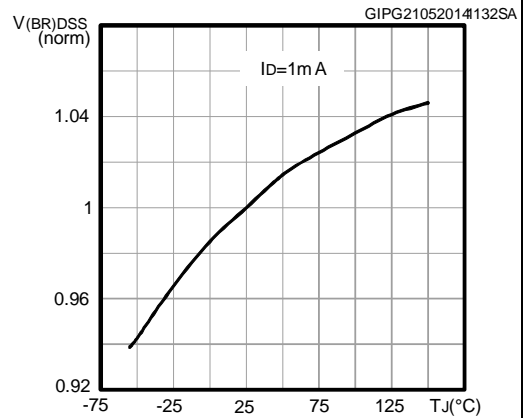
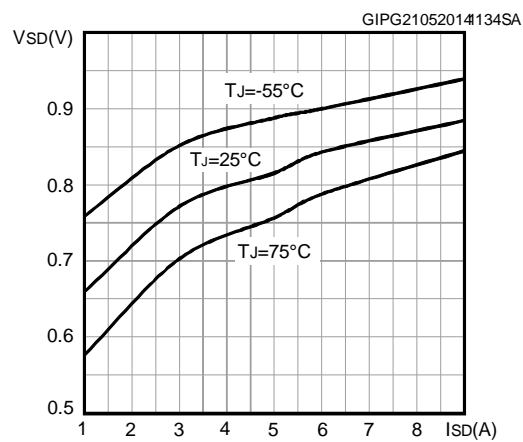
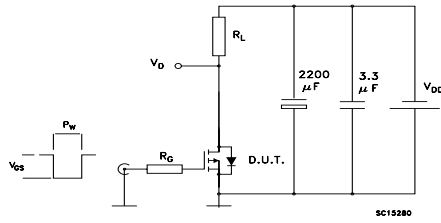


Figure 12: Source-drain diode forward characteristics



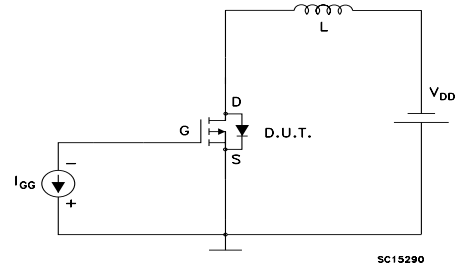
3 Test circuits

Figure 13: Switching times test circuit for resistive load



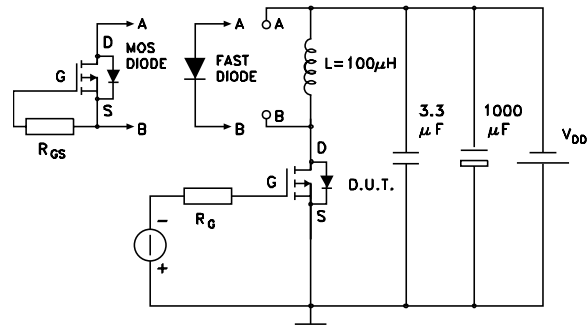
SC15280

Figure 14: Gate charge test circuit



SC15290

Figure 15: Test circuit for inductive load switching and diode recovery times



SC15300

4 Package mechanical data

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4.1 PowerFLAT™ 2x2 package mechanical data

Figure 16: Drawing dimension PowerFLAT™ 2 x 2

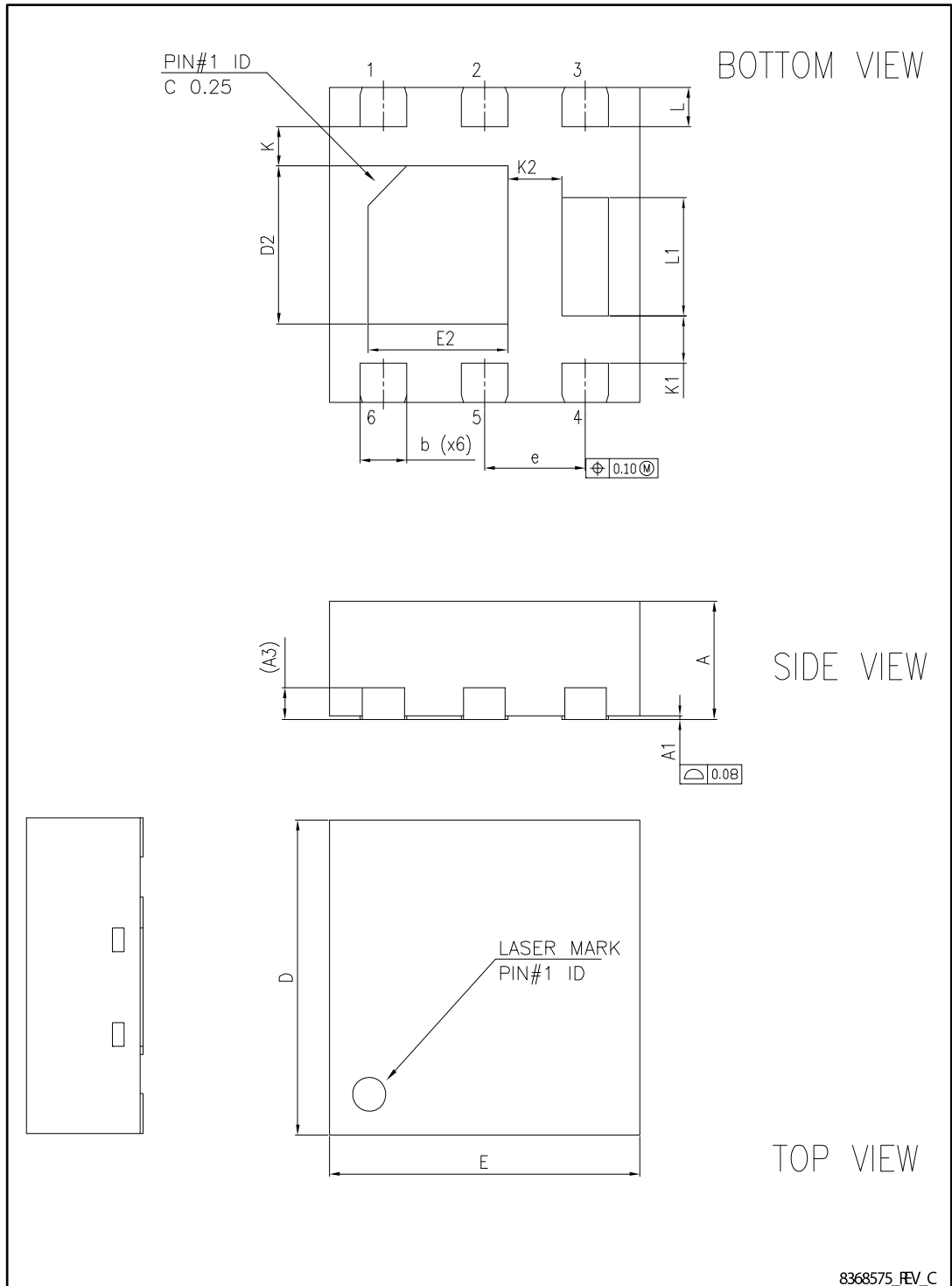
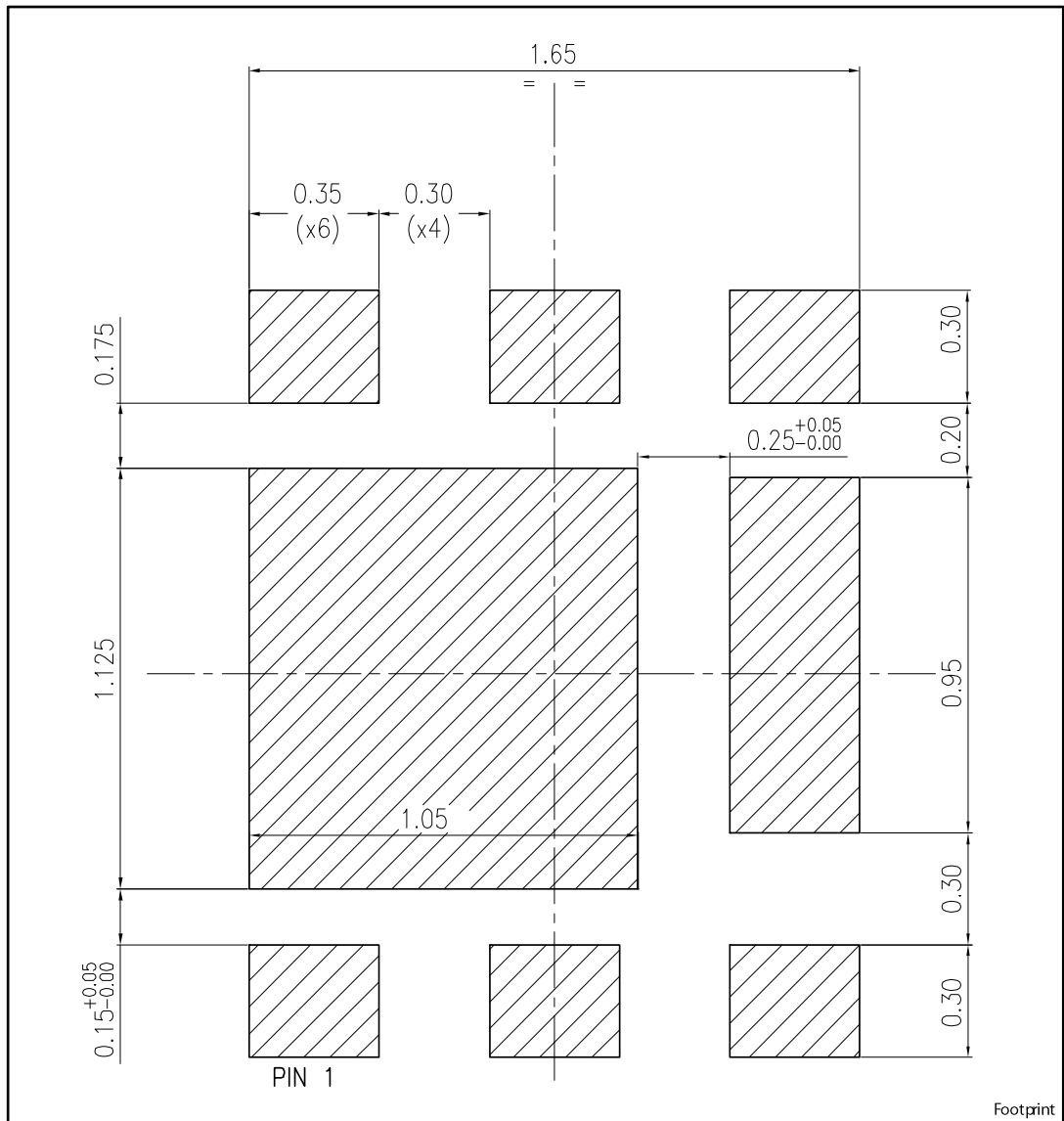


Table 8: PowerFLAT™ 2 x 2 mechanical data

| Dim. | mm. | | |
|------|------|------|------|
| | Min. | Typ. | Max. |
| A | 0.70 | 0.75 | 0.80 |
| A1 | 0.00 | 0.02 | 0.05 |
| A3 | | 0.20 | |
| b | 0.25 | 0.30 | 0.35 |
| D | 1.90 | 2.00 | 2.10 |
| E | 1.90 | 2.00 | 2.10 |
| D2 | 0.90 | 1.00 | 1.10 |
| E2 | 0.80 | 0.90 | 1.00 |
| e | 0.55 | 0.65 | 0.75 |
| K | 0.15 | 0.25 | 0.35 |
| K1 | 0.20 | 0.30 | 0.40 |
| K2 | 0.25 | 0.35 | 0.45 |
| L | 0.20 | 0.25 | 0.30 |
| L1 | 0.65 | 0.75 | 0.85 |

Figure 17: PowerFLAT™ 2 x 2 footprint



5 Revision history

Table 9: Document revision history

| Date | Revision | Changes |
|-------------|----------|--|
| 20-Aug-2013 | 1 | First release. |
| 04-Jun-2014 | 2 | Document status promoted from preliminary data to production data Modified: title Modified: $R_{DS(on)}$ max value in cover page Modified: $R_{DS(on)}$ (typical and maximum) values in Table 4: "On /off states" Modified: the entire typical values in Table 5: "Dynamic" , Table 6: "Switching times" and Table 7: "Source drain diode" Added Section 8.1: "Electrical characteristics (curves)" Minor text changes |

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